Fig.1

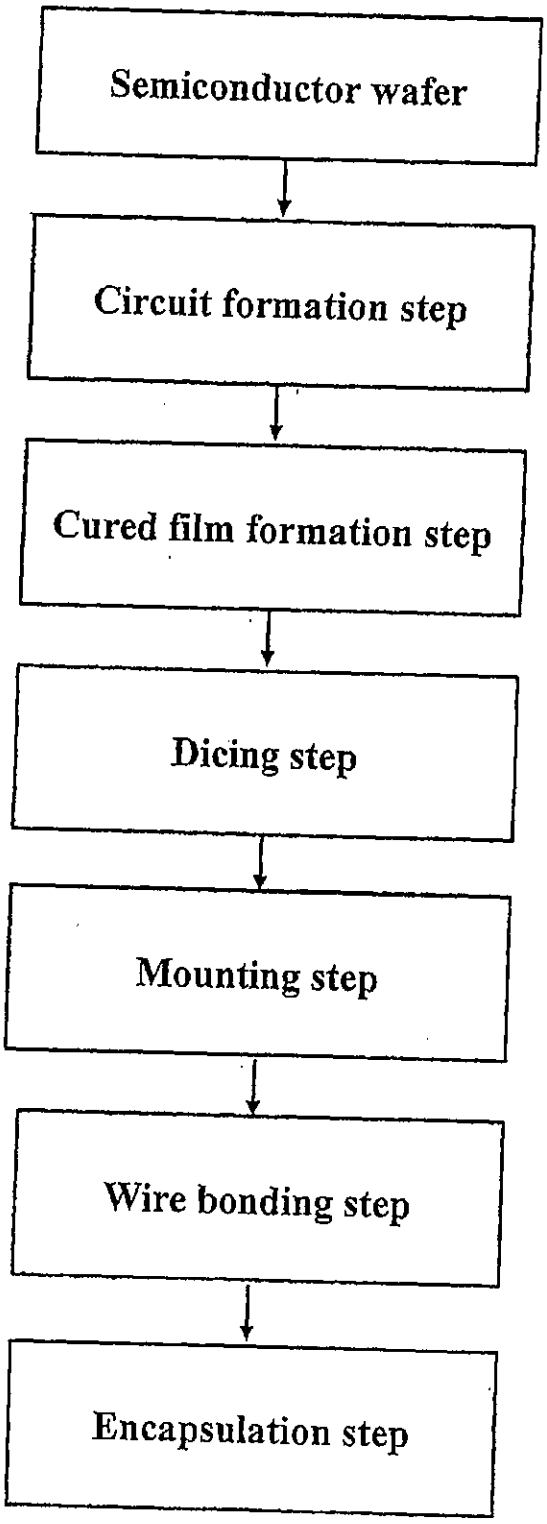

Semiconductor wafer
Circuit formation step
Cured film formation step
Dicing step
Mounting step
Wire bonding step
Encapsulation step

Fig.2

